

# P-N GaAs Infrared-Emitting Diode

Optoelectronic Products

## TIL38

### General Description

The TIL38 is a p-n GaAs infrared-emitting diode in a low-cost plastic T1-¾ package.

### Output Spectrally Compatible With Silicon Sensors

**High Power Output**

**High Radiant Intensity**

### Absolute Maximum Ratings

#### Maximum Temperature

Operating Temperature

-55°C to +100°C

Storage Temperature

-55°C to +100°C

Pin Temperature (Soldering, 3 s)

260°C

#### Maximum Power Dissipation

Total Dissipation at  $T_A = 25^\circ\text{C}$

125 mW

Derate Linearly at  $25^\circ\text{C}$

1.3 mW/°C

#### Maximum Voltage and Current

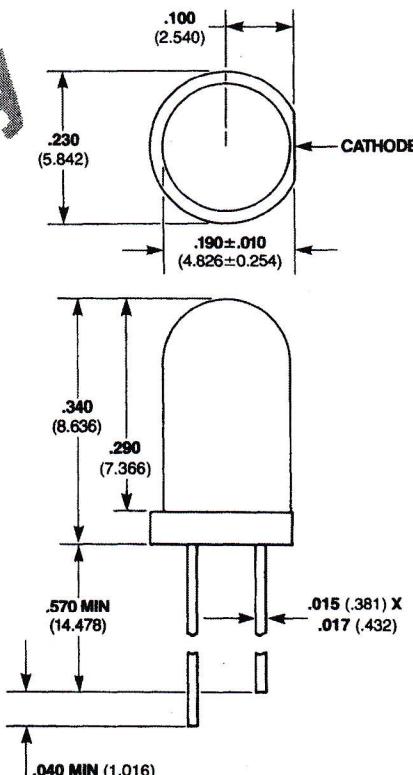
$V_R$  Reverse Voltage

5 V

$I_F$  Forward dc Current ( $25^\circ\text{C}$ )

150 mA

### Package Outline



### Notes

This device has a gray-tinted plastic body

All dimensions in inches bold and millimeters (parentheses)

Tolerance unless specified = ±.015 (±.381)

### Electrical Characteristics $T_A = 25^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Units	Test Conditions
$P_O$	Radiant Power Output	6	12		mW	$I_F = 100 \text{ mA}$
$\lambda_{pk}$	Wavelength @ Peak Emission	915	940	975	nm	$I_F = 100 \text{ mA}$
$\Delta\lambda$	Spectral Bandwidth Between Half-Power Points		50	75	nm	$I_F = 100 \text{ mA}$
$\theta_{HI}$	Emission Beam Angle Between Half Intensity		60		degree	$I_F = 100 \text{ mA}$
C	Capacitance		25		pF	$V_F = 0,$ $f = 1 \text{ MHz}$
$t_r$	Radiant Rise Time		600		ns	$I_{FM} = 20 \text{ mA},$ $t_w = 2 \mu\text{s}$
$t_f$	Radiant Fall Time		350		ns	$f = 45 \text{ kHz}$
$V_F$	Forward Voltage		2.55		V	$I_F = 1 \text{ A}$

# Silicon Photodiode

Optoelectronic Products

## TIL100

### General Description

The TIL100 is a high-speed PIN photodiode operating in a reverse-bias mode. It is spectrally matched with the TIL38 emitter. This photodiode was designed for infrared remote-control system.

### Low Capacitance

High Photosensitivity With Fast Response

### Absolute Maximum Ratings

#### Maximum Temperature

Operating Temperature

Storage Temperature

Pin Temperature (Soldering, 3 s)

**25°C to +100°C**  
**-25°C to +100°C**  
**260°C**

#### Maximum Power Dissipation

Total Dissipation at  $T_A = 25^\circ\text{C}$

**150 mW**

Derate Linearly at  $25^\circ\text{C}$

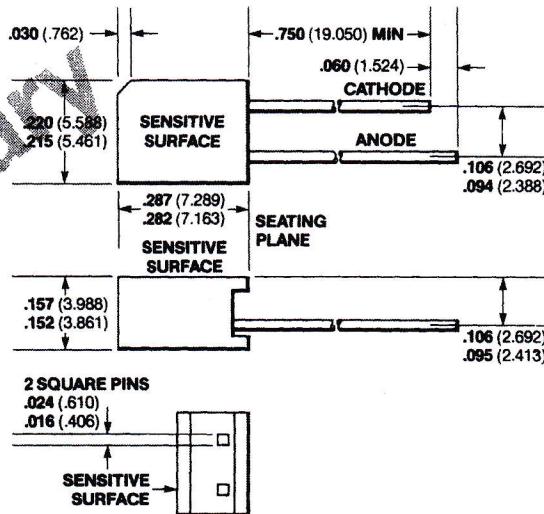
**2 mW/°C**

#### Maximum Voltage

BV Breakdown Voltage

**30 V**

### Package Outline



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### Notes

All dimensions in inches bold and millimeters (parentheses)

Tolerance unless specified =  $\pm .015$  ( $\pm .381$ )

### Electrical Characteristics $T_A = 25^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Units	Test Conditions
$C_T$	Total Capacitance		35	50	pF	$V_R = 3 \text{ V}$ , $H = 0$ , $f = 1 \text{ MHz}$
$t_r$	Rise Time			100	ns	$V_R = 10 \text{ V}$ , $R_L = 1 \text{ k}\Omega$
$t_f$	Fall Time			100	ns	$V_R = 10 \text{ V}$ , $R_L = 1 \text{ k}\Omega$
$I_L$	Light Current		10		$\mu\text{A}$	$V_R = 10 \text{ V}$ , $H = 250 \text{ W/cm}^2$ at 940 nm
$I_D$	Dark Current			50	nA	$V_R = 10 \text{ V}$ , $H = 0$